

Global Flip Chip Bonder Market Data Survey Report 2025

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Abstracts

SUMMARY

Flip chip is a method used for components or devices that can be bonded directly onto a substrate, board or carrier face-down. The connection is made through conductive bumps placed on the surface of the die. The placing process amounts to the following:

The global Flip Chip Bonder market will reach Volume Million USD in 2017 with CAGR xx% 2018-2025. The main contents of the report including:

Global market size and forecast

Regional market size, production data and export & import

Key manufacturers (manufacturing sites, capacity and production, product specifications etc.)

Average market price by SUK

Major applications

Key manufacturers are included based on manufacturing sites, capacity and production, product specifications etc.:

Besi

ASM Pacific Technology

Shibaura

Muehlbauer

Kulicke & Soffa

Hamni

AMICRA Microtechnologies

SET

Major applications as follows:

IDMs

OSAT

Regional market size, production data and export & import:

Asia-Pacific

North America

Europe

South America

Middle East & Africa

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